



# SMD Power Inductor

TMPF0603A-Series(N)-D

## 1. Features

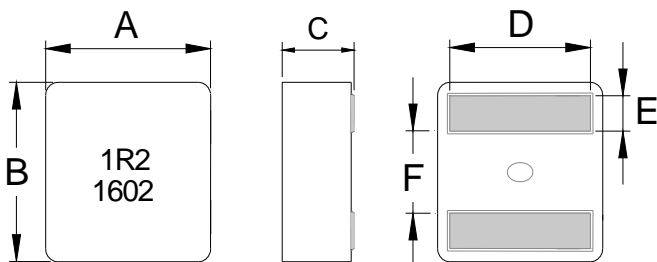
1. Soft saturation.
2. High current · low DCR · high efficiency.
3. Very low acoustic noise and very low leakage flux noise.
4. High reliability.
5. 100% Lead(Pb)-Free and RoHS compliant.



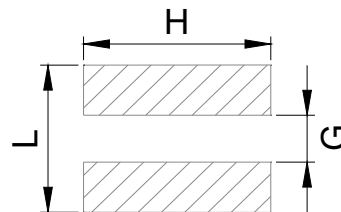
## 2. Applications

Note PC power system · incl. IMVP-6  
DC/DC converter .

## 3. Dimensions



### Recommend PC Board Pattern



L(mm)	G(mm)	H(mm)
5.6 ref	2.5 ref	5.6 ref

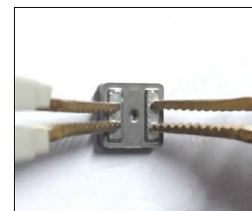
Note: 1、 The above PCB layout reference only.  
2、 Recommend solder paste thickness at 0.15mm and above.

Series	Inductance Range	A (mm)	B (mm)	C (mm)	D (mm)	E (mm)	F (mm)
TMPF0603A	1.2uH and below	6.6±0.2	6.4±0.2	2.8±0.2	See Spec table	1.4±0.2	2.6±0.25
	1.5uH and above			2.9±0.2			

## 4. Part Numbering



- A: Series
  - B: Dimension
  - C: Type
  - D: Inductance
  - E: Inductance Tolerance
  - F: Code
- BxC
  - Material.
  - 1R2=1.20uH
  - M=±20%
  - Marking: Black.1R2 and 1602(16 YY, 02 WW, follow production date).



DCR Test

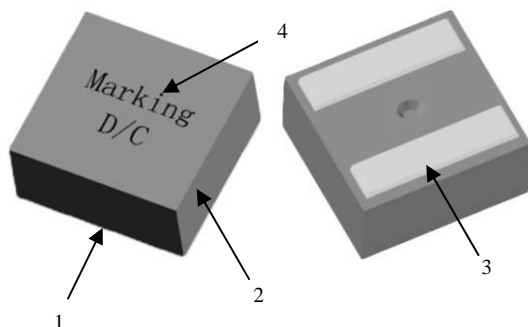
## 5. Specification

Part Number	Inductance( $\mu$ H) $\pm 20\%$ @ 0 A	I rms(A) Typ		I sat(A)		DCR (m $\Omega$ ) Typ.	DCR (m $\Omega$ ) Max.	D(mm) $\pm 0.3$
		20 $^{\circ}$ C rise	40 $^{\circ}$ C rise	Typ	Max			
TMPF0603A-R18MN-D	0.18	24.0	32.0	40.0	36.0	1.60	1.75	5.30
TMPF0603A-R33MN-D	0.33	20.0	25.0	32.0	28.0	2.25	2.50	5.55
TMPF0603A-R56MN-D	0.56	17.0	22.0	29.0	25.0	3.00	3.31	5.30
TMPF0603A-1R0MN-D	1.00	13.0	18.0	23.0	18.0	5.50	6.05	5.20
TMPF0603A-1R2MN-D	1.20	12.0	16.0	22.0	16.0	6.70	7.40	5.15
TMPF0603A-1R8MN-D	1.80	10.0	14.0	18.2	13.0	9.20	10.2	5.10
TMPF0603A-2R2MN-D	2.20	7.00	10.0	15.9	11.0	11.0	12.2	5.05
TMPF0603A-3R3MN-D	3.30	6.00	8.00	12.2	9.00	18.8	20.8	5.00
TMPF0603A-4R5MN-D	4.50	5.00	7.00	10.0	8.00	23.0	25.3	5.00

Note:

1. Test frequency : L : 100KHz /0.1V.
2. All test data referenced to 25 $^{\circ}$ C ambient.
3. Testing Instrument : L: HP4284A,HP4395A,CH11025,CH3302,CH1320 ,CH1320S LCR METER / Rdc:CH16502,Agilent33420A MICRO OHMMETER,or EQU.
4. Current that causes the specified temperature rise from 25 $^{\circ}$ C ambient.
5. Saturation Current (Isat) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 125 $^{\circ}$ C under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. Special inquiries besides the above common used types can be met on your requirement.

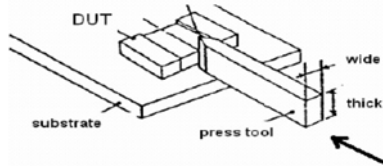
## 6. Material List



NO	Items	Materials
1	Core	Alloy powder.
2	Wire	Polyester Wire or equivalent.
3	Solder	100% Pb free solder
4	Ink	Halogen-free ketone

### 7. Reliability and Test Condition

Item	Performance	Test Condition
Operating temperature	-40~+125°C (Including self - temperature rise)	
Storage temperature	1.-10~+40°C,50~60%RH (Product without taping) 2.-40~+125°C (on board)	
<b>Electrical Performance Test</b>		
Inductance	Refer to standard electrical characteristics list.	HP4284A,CH11025,CH3302,CH1320,CH1320S LCR Meter.
DCR		CH16502,Agilent33420A Micro-Ohm Meter.
Saturation Current (Isat)	Approximately ΔL30%.	Saturation DC Current (Isat) will cause L0 to drop ΔL(%).
Heat Rated Current (Irms)	Approximately ΔT 20°C Approximately ΔT 40°C	Heat Rated Current (Irms) will cause the coil temperature rise ΔT(°C). 1.Applied the allowed DC current. 2.Temperature measured by digital surface thermometer
<b>Reliability Test</b>		
Life Test	Appearance : No damage. Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020DClassification Reflow Profiles) Temperature : 125±2°C(Inductor) Applied current : rated current Duration : 1000±12hrs Measured at room temperature after placing for 24±2 hrs
Load Humidity		Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020DClassification Reflow Profiles) Humidity : 85±2% R.H, Temperature : 85°C±2°C Duration : 1000hrs Min. with 100% rated current Measured at room temperature after placing for 24±2 hrs
Moisture Resistance		Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020DClassification Reflow Profiles) 1. Baked at50°C for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs. 3. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs,keep at 25°C for 2 hrs then keep at -10°C for 3 hrs 4. Keep at 25°C 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.
Thermal shock		Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020DClassification Reflow Profiles) Condition for 1 cycle Step1 : -40±2°C 30±5min Step2 : 25±2°C ≤0.5min Step3 : 125±2°C 30±5min Number of cycles : 500 Measured at room temperature after placing for 24±2 hrs
Vibration		Oscillation Frequency: 10 ~ 2K ~ 10Hz for 20 minutes Equipment : Vibration checker Total Amplitude:1.52mm±10% Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations).

Item	Performance	Test Condition															
Shock	Appearance : No damage. Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value	<table border="1"> <thead> <tr> <th>Type</th> <th>Peak value (g's)</th> <th>Normal duration (D) (ms)</th> <th>Wave form</th> <th>Velocity change (V)ft/sec</th> </tr> </thead> <tbody> <tr> <td>SMD</td> <td>50</td> <td>11</td> <td>Half-sine</td> <td>11.3</td> </tr> <tr> <td>Lead</td> <td>50</td> <td>11</td> <td>Half-sine</td> <td>11.3</td> </tr> </tbody> </table>	Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (V)ft/sec	SMD	50	11	Half-sine	11.3	Lead	50	11	Half-sine	11.3
Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (V)ft/sec													
SMD	50	11	Half-sine	11.3													
Lead	50	11	Half-sine	11.3													
Bending		Shall be mounted on a FR4 substrate of the following dimensions: >=0805:40x100x1.2mm <0805:40x100x0.8mm Bending depth: >=0805:1.2mm <0805:0.8mm duration of 10 sec.															
Solderability	More than 95% of the terminal electrode should be covered with solder.	Preheat: 150°C,60sec. Solder: Sn96.5% Ag3% Cu0.5% Temperature: 245±5°C Flux for lead free: Rosin. 9.5%. Dip time: 4±1sec. Depth: completely cover the termination															
Resistance to Soldering Heat		Number of heat cycles: 1  <table border="1"> <thead> <tr> <th>Temperature (°C)</th> <th>Time(s)</th> <th>Temperature ramp/immersion and emersion rate</th> </tr> </thead> <tbody> <tr> <td>260 ±5(solder temp)</td> <td>10 ±1</td> <td>25mm/s ±6 mm/s</td> </tr> </tbody> </table>	Temperature (°C)	Time(s)	Temperature ramp/immersion and emersion rate	260 ±5(solder temp)	10 ±1	25mm/s ±6 mm/s									
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260 ±5(solder temp)	10 ±1	25mm/s ±6 mm/s															
Terminal Strength	Appearance : No damage. Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020DClassification Reflow Profiles With the component mounted on a PCB with the device to be tested, apply a force (>0805:1kg , <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.  															

Note : When there are questions concerning measurement result : measurement shall be made after 48 ± 2 hours of recovery under the standard condition.

## 8. Soldering and Mounting

### (1) Soldering

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. TAI-TECH terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

### (2) Solder re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

### (3) Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

- Preheat circuit and products to 150°C
- Never contact the ceramic with the iron tip
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- 355°C tip temperature (max)
- 1.0mm tip diameter (max)
- Limit soldering time to 4-5sec.

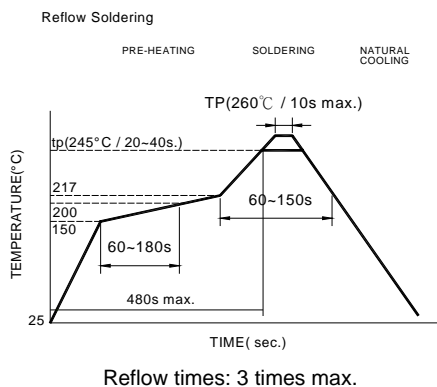


Fig.1

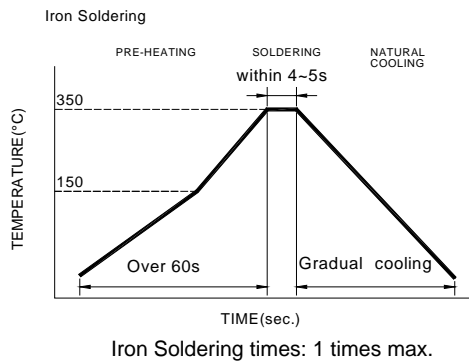


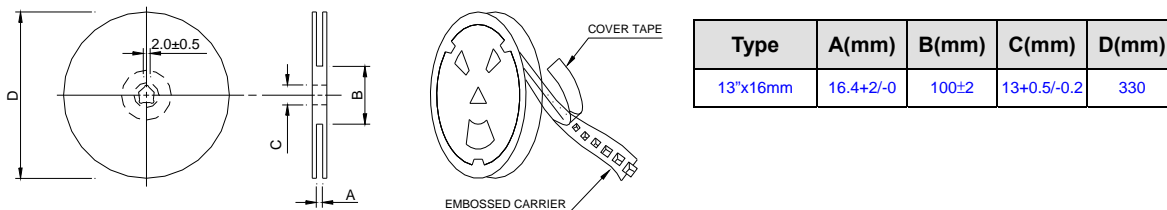
Fig.2

## 9. Friendly reminder

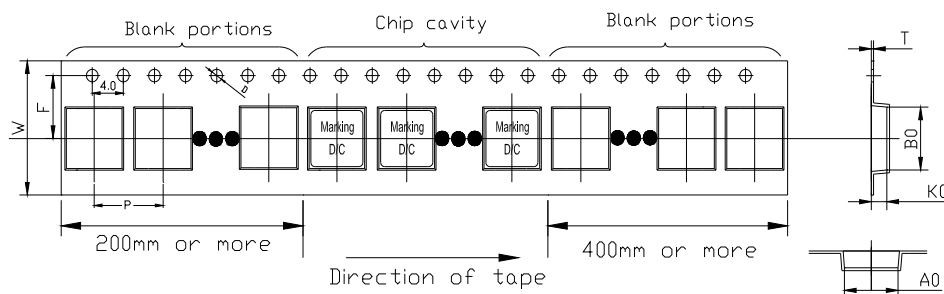
- (1) When there are questions concerning measurement result : measurement shall be made after 48 ± 2 hours of recovery under the standard condition
- (2) This power choke coil itself does not have any protective function in abnormal condition such as overload, short-circuit and open-circuit conditions, etc. Therefore, it shall be confirmed as the end product that there is no risk of smoking, fire, dielectric withstand voltage, insulation resistance, etc. in abnormal conditions to provide protective devices and/or protection circuit in the end product.
- (3) When this power choke coil was used in a similar or new product to the original one, sometimes it might not be able to satisfy the specifications due to different condition of use.
- (4) Dielectric withstanding test with higher voltage than specific value will damage insulating material and shorten its life.
- (5) This power choke coil must not be used in wet condition by water, coffee or any liquid because insulation strength becomes very low in this condition.
- (6) Please consult our company to confirm the reliability of the process required to wash or use or exposure to a chemical solvent used in this product. PCB washing tested to MIL-STD-202 Method. Use only alcohol to wash the PCB and dry it off immediately (Marking will be washed away if using alcohol).

### 10. Packaging Information

#### (1) Reel Dimension



#### (2) Tape Dimension



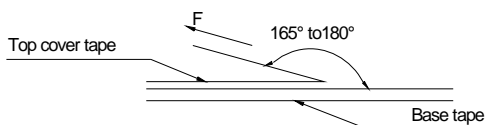
Series	Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	W(mm)	F(mm)	T(mm)	D(mm)
TMPF	0603	6.8±0.1	7.0±0.1	3.3±0.1	12.0±0.1	16±0.3	7.5±0.1	0.35±0.05	1.5±0.1

#### (3) Packaging Quantity

TMPF	0603
Chip / Reel	1000
Inner box	2000
Carton	8000

#### (4) Tearing Off Force

The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions(referenced ANSI/EIA-481-C-2003 of 4.11 standard).

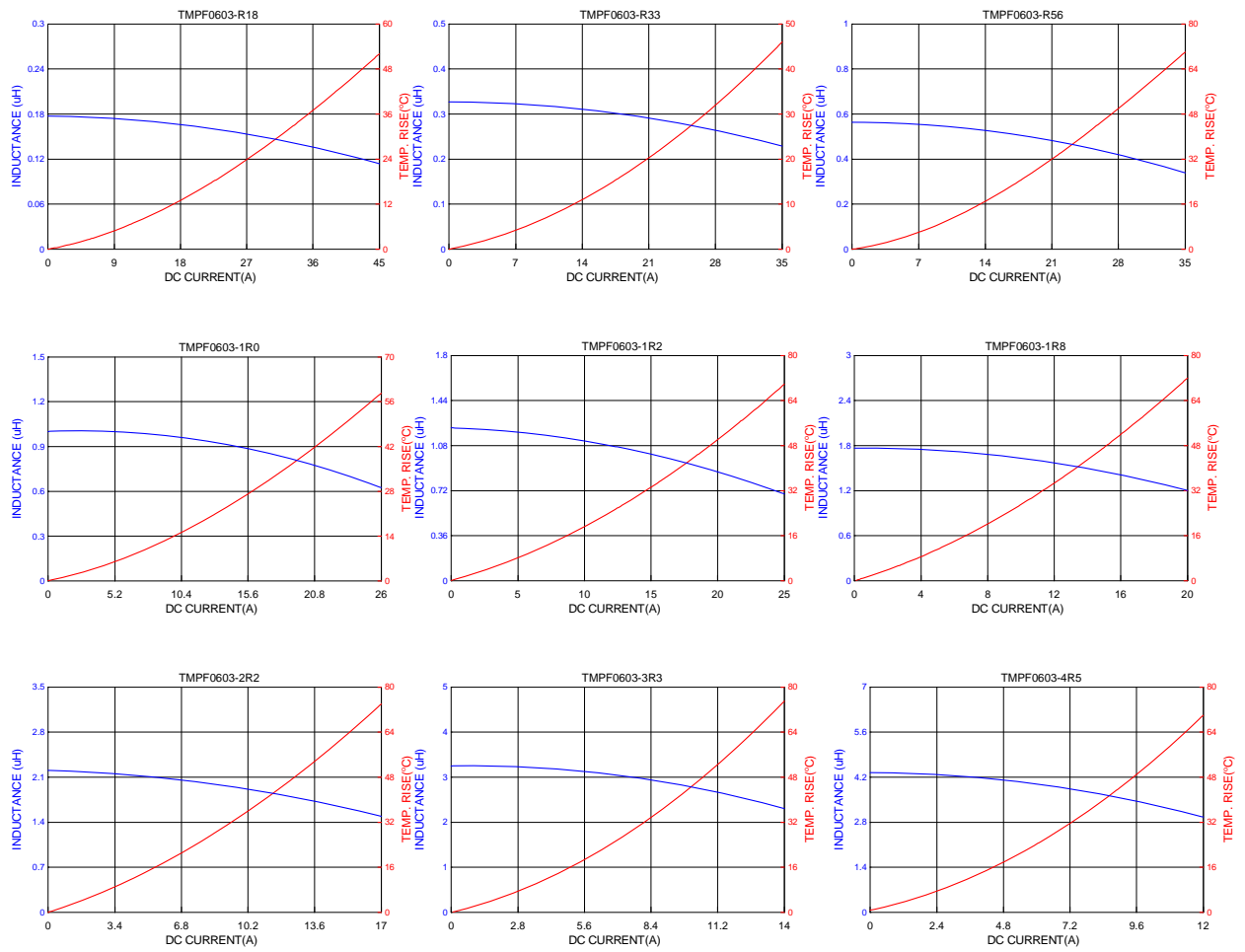


Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

#### Application Notice

- Storage Conditions
  - To maintain the solderability of terminal electrodes:
    1. TAIPAQ products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
    2. Temperature and humidity conditions: Less than 40°C and 60% RH.
    3. Recommended products should be used within 12 months form the time of delivery.
    4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
  1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
  2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
  3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

### 11. Typical Performance Curves





## 12、 Appearance criterion

### 1、 PAD residual powder、 imprinting

The residual powder on both side of pad is norm and within following criteria are acceptable.

The imprinting mark below the part, are norm in manufacturing process and does not affect the function and it is acceptable.

Front lit imprinting is acceptable.

<b>a</b>	10% max of the length of pad.
<b>b</b>	5% of the area on one single pad.
<b>t</b>	0.08mm max.

### 2、 Defects

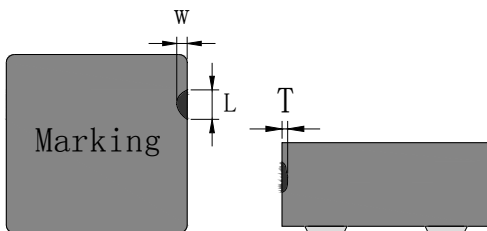
Foreign materials on the product body is inevitable and accepted.

Chip off is generated during molding and manufacturing process.

Chip off acceptance limits subjected to the product size.

Our current Defect limit is based on the IPC-A-610.

Some chip off does not impact the product function, see the IPC standard 1 & 2.



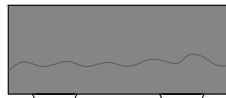
<b>T</b>	25 % of the thickness
<b>W</b>	25 % of the width
<b>L</b>	50 % of the length

Defects usually occur at the corners and edges of the product, There will be a slight defect black and rough, but not exposed copper, and does not affect the product performance and reliability.

### 3、 Crack

Production process of cracks appearing in the body is inevitable, some slight crack is caused because the molding, is not oxidized, crack on the product will not affect product performance.

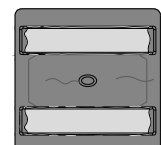
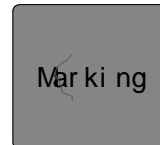
We have done a reliability test of crack products, even if cracks is more than 0.13mm also will not affect the electrical properties of the product, crack limits as follows.



Severely crack: not acceptable.  
More obvious cracks extended from side to side.



Moderate crack: not acceptable.  
Very obvious and may result in powder come off and exposed of copper wire.



Slight crack: acceptable.

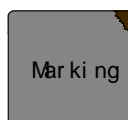
Products from a slight crack in the baking process due to thermal expansion, and it is not obvious by visual inspection.

### 4、 oxidation(rust)

the contains iron composite, although the resin has a protective effect of oxidation, but there will be small amount of product that may occur oxidation. it is recommend that customer use this product in humidity controlled environment. The basic steps should be to protect the surface oxidation, including the sealed packages to PCB mount inductors. To avoid the adverse effects caused by oxidation, Oxidation occurs at the surface only allows the internal oxidation is not allowed, oxidized surface will not affect the reliability of the product.



4sides slightly oxidized side:  
Acceptable



Top and bottom slightly oxidized side:  
Acceptable



Ps: Spray printing effect :  
can be accepted if recognizable

## 測試報告 Test Report

號碼(No.) : CE/2016/A0549

日期(Date) : 2016/10/13

頁數(Page): 1 of 12

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(耀鑽科技股份有限公司 / YOSONIC TECHNOLOGY CO., LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 / NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市蓬朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(桃園市中壢區中壢工業區長春六路15號 / NO. 15, CHANGCHUN 6TH RD., JHONGLI CITY, TAOYUAN COUNTY 320, TAIWAN)

(中國江蘇省宿遷市泗洪縣經濟開發區杭州路南側建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P. R. CHINA)

以下測試樣品係由申請廠商所提供及確認 (The following sample(s) was/were submitted and identified by/on behalf of the applicant as):

樣品名稱(Sample Description) : SMD POWER INDUCTOR  
樣品型號(Style/Item No.) : TMPB、TMPC、TMPA、TMPF、SLPI、SMPI、EPI(ePI)、VMPI、MLPI SERIES  
收件日期(Sample Receiving Date) : 2016/10/05  
測試期間(Testing Period) : 2016/10/05 TO 2016/10/13

### 測試需求(Test Requested):

- (1) 依據客戶指定, 參考RoHS2011/65/EU Annex II及其修訂指令(EU) 2015/863測試鎘、鉛、汞、六價鉻、多溴聯苯、多溴聯苯醚, DBP, BBP, DEHP, DIBP. (As specified by client, with reference to RoHS 2011/65/EU Annex II and amending Directive (EU) 2015/863 to determine Cadmium, Lead, Mercury, Cr(VI), PBBs, PBDEs, DBP, BBP, DEHP, DIBP contents in the submitted sample.)
- (2) 其他測試項目請見下一頁. (Please refer to next pages for the other item(s).)

測試結果(Test Results) : 請見下一頁 (Please refer to next pages).

Troy Chang, Manager - Tech  
Signed for and on behalf of  
SGS TAIWAN LTD.  
Chemical Laboratory - Taipei





# 測試報告

## Test Report

號碼(No.) : CE/2016/A0549

日期(Date) : 2016/10/13

頁數(Page): 2 of 12

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(耀鑽科技股份有限公司 / YOSONIC TECHNOLOGY CO., LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 / NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市蓬明昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(桃園市中壢區中壢工業區長春六路15號 / NO. 15, CHANGCHUN 6TH RD., JHONGLI CITY, TAOYUAN COUNTY 320, TAIWAN)

(中國江蘇省宿遷市泗洪縣經濟開發區杭州路南側建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P. R. CHINA)

### 測試結果(Test Results)

測試部位(PART NAME)No. 1 : 整體混測 (MIXED ALL PARTS)

測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限值 (MDL)	結果 (Result)
				No. 1
鎘 / Cadmium (Cd)	mg/kg	參考IEC 62321-5 (2013), 以感應耦合電漿原子發射光譜儀檢測. / With reference to IEC 62321-5 (2013) and performed by ICP-AES.	2	n. d.
鉛 / Lead (Pb)	mg/kg	參考IEC 62321-5 (2013), 以感應耦合電漿原子發射光譜儀檢測. / With reference to IEC 62321-5 (2013) and performed by ICP-AES.	2	n. d.
汞 / Mercury (Hg)	mg/kg	參考IEC 62321-4 (2013), 以感應耦合電漿原子發射光譜儀檢測. / With reference to IEC 62321-4 (2013) and performed by ICP-AES.	2	n. d.
六價鉻 / Hexavalent Chromium Cr(VI)	mg/kg	參考IEC 62321 (2008), 以UV-VIS檢測. / With reference to IEC 62321 (2008) and performed by UV-VIS.	2	n. d.
鈹 / Beryllium (Be)	mg/kg	參考US EPA 3052 (1996), 以感應耦合電漿原子發射光譜儀檢測. / With reference to US EPA 3052 (1996). Analysis was performed by ICP-AES.	2	n. d.
銻 / Antimony (Sb)	mg/kg	參考US EPA 3052 (1996), 以感應耦合電漿原子發射光譜儀檢測. / With reference to US EPA 3052 (1996). Analysis was performed by ICP-AES.	2	n. d.

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# 測試報告

## Test Report

號碼(No.) : CE/2016/A0549

日期(Date) : 2016/10/13

頁數(Page): 3 of 12

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

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測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限值 (MDL)	結果 (Result)
				No. 1
六溴環十二烷及所有主要被辨別出的異構物 / Hexabromocyclododecane (HBCDD) and all major diastereoisomers identified ( $\alpha$ -HBCDD, $\beta$ -HBCDD, $\gamma$ -HBCDD) (CAS No.: 25637-99-4 and 3194-55-6 (134237-51-7, 134237-50-6, 134237-52-8))	mg/kg	參考IEC 62321 (2008), 以氣相層析/質譜儀檢測. / With reference to IEC 62321 (2008). Analysis was performed by GC/MS.	5	n. d.
<b>鹵素 / Halogen</b>				
鹵素 (氟) / Halogen-Fluorine (F) (CAS No.: 14762-94-8)	mg/kg	參考BS EN 14582 (2007), 以離子層析儀分析. / With reference to BS EN 14582 (2007). Analysis was performed by IC.	50	n. d.
鹵素 (氯) / Halogen-Chlorine (Cl) (CAS No.: 22537-15-1)	mg/kg		50	n. d.
鹵素 (溴) / Halogen-Bromine (Br) (CAS No.: 10097-32-2)	mg/kg		50	n. d.
鹵素 (碘) / Halogen-Iodine (I) (CAS No.: 14362-44-8)	mg/kg		50	n. d.
鄰苯二甲酸丁苯甲酯 / BBP (Butyl Benzyl phthalate) (CAS No.: 85-68-7)	mg/kg	參考IEC 62321-8/CD (2013), 以氣相層析儀/質譜儀檢測. / With reference to IEC 62321-8/CD (2013). Analysis was performed by GC/MS.	50	n. d.
鄰苯二甲酸二丁酯 / DBP (Dibutyl phthalate) (CAS No.: 84-74-2)	mg/kg		50	n. d.
鄰苯二甲酸二(2-乙基己基)酯 / DEHP (Di-(2-ethylhexyl) phthalate) (CAS No.: 117-81-7)	mg/kg		50	n. d.

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# 測試報告

## Test Report

號碼(No.) : CE/2016/A0549

日期(Date) : 2016/10/13

頁數(Page): 4 of 12

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測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限值 (MDL)	結果 (Result)
				No. 1
鄰苯二甲酸二異丁酯 / DIBP (Di-isobutyl phthalate) (CAS No. : 84-69-5)	mg/kg	參考 IEC 62321-8/CD (2013), 以氣相層析儀/質譜儀檢測。 / With reference to IEC 62321-8/CD (2013). Analysis was performed by GC/MS.	50	n. d.
鄰苯二甲酸二異癸酯 / DIDP (Di-isodecyl phthalate) (CAS No. : 26761-40-0; 68515-49-1)	mg/kg		50	n. d.
鄰苯二甲酸二異壬酯 / DINP (Di-isononyl phthalate) (CAS No. : 28553-12-0; 68515-48-0)	mg/kg		50	n. d.
鄰苯二甲酸二正辛酯 / DNOP (Di-n-octyl phthalate) (CAS No. : 117-84-0)	mg/kg		50	n. d.
鄰苯二甲酸二正己酯 / DNHP (Di-n-hexyl phthalate) (CAS No. : 84-75-3)	mg/kg		50	n. d.
鄰苯二甲酸二戊酯 / Di-n-pentyl phthalate (CAS No. : 131-18-0)	mg/kg		50	n. d.
多溴聯苯總和 / Sum of PBBs	mg/kg	參考 IEC 62321-6 (2015), 以氣相層析儀/質譜儀檢測。 / With reference to IEC 62321-6 (2015) and performed by GC/MS.	-	n. d.
一溴聯苯 / Monobromobiphenyl	mg/kg		5	n. d.
二溴聯苯 / Dibromobiphenyl	mg/kg		5	n. d.
三溴聯苯 / Tribromobiphenyl	mg/kg		5	n. d.
四溴聯苯 / Tetrabromobiphenyl	mg/kg		5	n. d.
五溴聯苯 / Pentabromobiphenyl	mg/kg		5	n. d.
六溴聯苯 / Hexabromobiphenyl	mg/kg		5	n. d.
七溴聯苯 / Heptabromobiphenyl	mg/kg		5	n. d.
八溴聯苯 / Octabromobiphenyl	mg/kg		5	n. d.
九溴聯苯 / Nonabromobiphenyl	mg/kg		5	n. d.
十溴聯苯 / Decabromobiphenyl	mg/kg	5	n. d.	

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## Test Report

號碼(No.) : CE/2016/A0549

日期(Date) : 2016/10/13

頁數(Page): 5 of 12

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測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限值 (MDL)	結果 (Result)
				No. 1
多溴聯苯醚總和 / Sum of PBDEs	mg/kg	參考 IEC 62321-6 (2015), 以氣相層析 / 質譜儀檢測. / With reference to IEC 62321-6 (2015) and performed by GC/MS.	-	n. d.
一溴聯苯醚 / Monobromodiphenyl ether	mg/kg		5	n. d.
二溴聯苯醚 / Dibromodiphenyl ether	mg/kg		5	n. d.
三溴聯苯醚 / Tribromodiphenyl ether	mg/kg		5	n. d.
四溴聯苯醚 / Tetrabromodiphenyl ether	mg/kg		5	n. d.
五溴聯苯醚 / Pentabromodiphenyl ether	mg/kg		5	n. d.
六溴聯苯醚 / Hexabromodiphenyl ether	mg/kg		5	n. d.
七溴聯苯醚 / Heptabromodiphenyl ether	mg/kg		5	n. d.
八溴聯苯醚 / Octabromodiphenyl ether	mg/kg		5	n. d.
九溴聯苯醚 / Nonabromodiphenyl ether	mg/kg		5	n. d.
十溴聯苯醚 / Decabromodiphenyl ether	mg/kg	5	n. d.	

### 備註(Note) :

1. mg/kg = ppm ; 0.1wt% = 1000ppm
2. n. d. = Not Detected (未檢出)
3. MDL = Method Detection Limit (方法偵測極限值)
4. "-" = Not Regulated (無規格值)

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## 測試報告 Test Report

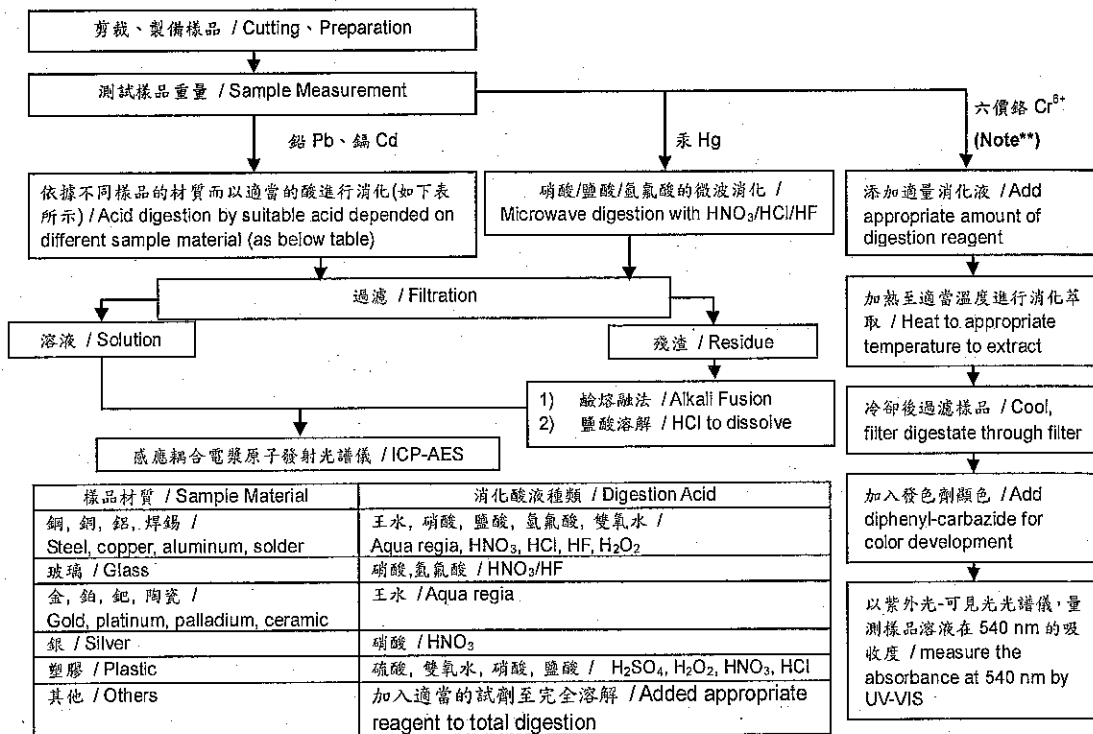
號碼(No.) : CE/2016/A0549 日期(Date) : 2016/10/13 頁數(Page): 6 of 12

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### 重金屬流程圖 / Analytical flow chart of Heavy Metal (IEC 62321)

根據以下的流程圖之條件，樣品已完全溶解。(六價鉻測試方法除外) /  
 These samples were dissolved totally by pre-conditioning method according to below flow chart. (Cr<sup>6+</sup> test method excluded)

- 測試人員: 王志瑋 / Technician: JR Wang
- 測試負責人: 張啟興 / Supervisor: Troy Chang



Notes: (1) 針對非金屬材料加入鹼性消化液，加熱至 90~95°C 萃取。 / For non-metallic material, add alkaline digestion reagent and heat to 90~95°C.  
 (2) 針對金屬材料加入純水，加熱至沸騰萃取。 / For metallic material, add pure water and heat to boiling



# 測試報告 Test Report

號碼(No.) : CE/2016/A0549

日期(Date) : 2016/10/13

頁數(Page): 7 of 12

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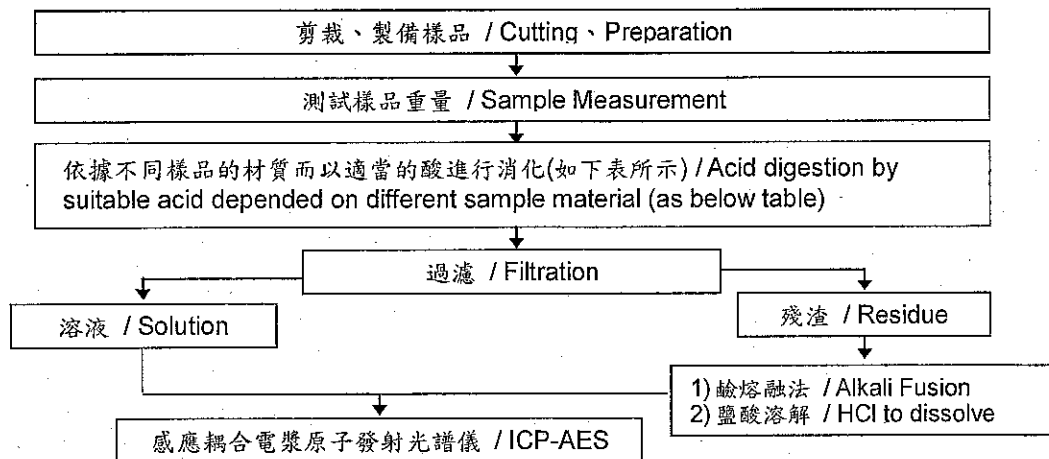
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根據以下的流程圖之條件，樣品已完全溶解。 / These samples were dissolved totally by pre-conditioning method according to below flow chart.

- 測試人員：王志瑋 / Technician: JR Wang
- 測試負責人：張啟興 / Supervisor: Troy Chang

元素以 ICP-AES 分析的消化流程圖  
(Flow Chart of digestion for the elements analysis performed by ICP-AES)



鋼,銅,鋁,焊錫 / Steel, copper, aluminum, solder	王水,硝酸,鹽酸,氫氟酸,雙氧水 / Aqua regia, HNO <sub>3</sub> , HCl, HF, H <sub>2</sub> O <sub>2</sub>
玻璃 / Glass	硝酸,氫氟酸 / HNO <sub>3</sub> /HF
金,鉑,鈀,陶瓷 / Gold, platinum, palladium, ceramic	王水 / Aqua regia
銀 / Silver	硝酸 / HNO <sub>3</sub>
塑膠 / Plastic	硫酸,雙氧水,硝酸,鹽酸 / H <sub>2</sub> SO <sub>4</sub> , H <sub>2</sub> O <sub>2</sub> , HNO <sub>3</sub> , HCl
其他 / Others	加入適當的試劑至完全溶解 / Added appropriate reagent to total digestion

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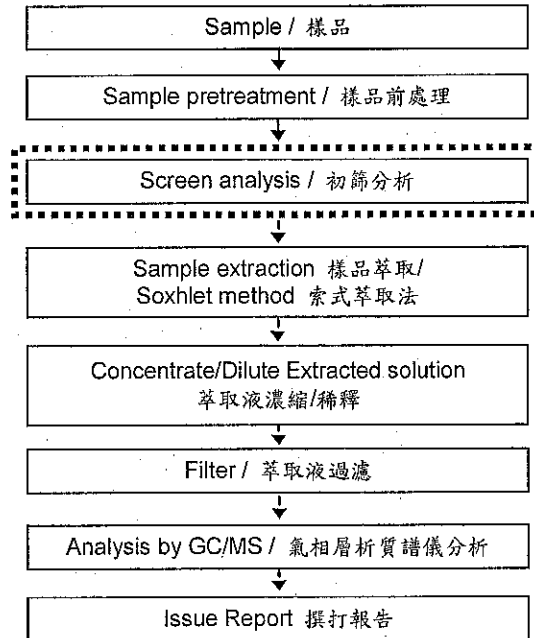
號碼(No.) : CE/2016/A0549      日期(Date) : 2016/10/13      頁數(Page): 8 of 12

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## 多溴聯苯/多溴聯苯醚分析流程圖 / Analytical flow chart - PBB/PBDE

- 測試人員：涂雅苓 / Technician: Yaling Tu
- 測試負責人：張啟興 / Supervisor: Troy Chang

初次測試程序 / First testing process —————>  
 選擇性篩檢程序 / Optional screen process .....  
 確認程序 / Confirmation process - - - ->



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## 測試報告 Test Report

號碼(No.) : CE/2016/A0549

日期(Date) : 2016/10/13

頁數(Page): 9 of 12

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

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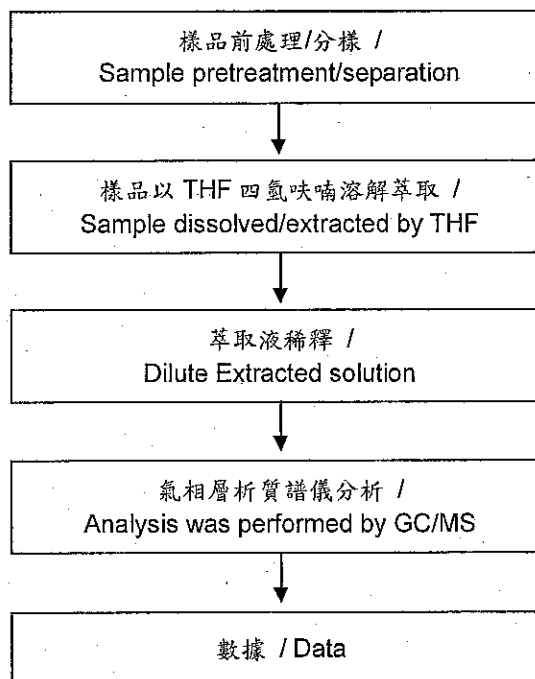
(桃園市中壢區中壢工業區長春六路15號 / NO. 15, CHANGCHUN 6TH RD., JHONGLI CITY, TAOYUAN COUNTY 320, TAIWAN)

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### 可塑劑分析流程圖 / Analytical flow chart - Phthalate

- 測試人員：徐毓明 / Technician: Andy Shu
- 測試負責人：張啟興 / Supervisor : Troy Chang

【測試方法/Test method: IEC 62321-8】



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## 六溴環十二烷分析流程圖 / Analytical flow chart - HBCDD


- 測試人員：涂雅苓 / Technician: Yaling Tu
- 測試負責人：張啟興 / Supervisor: Troy Chang



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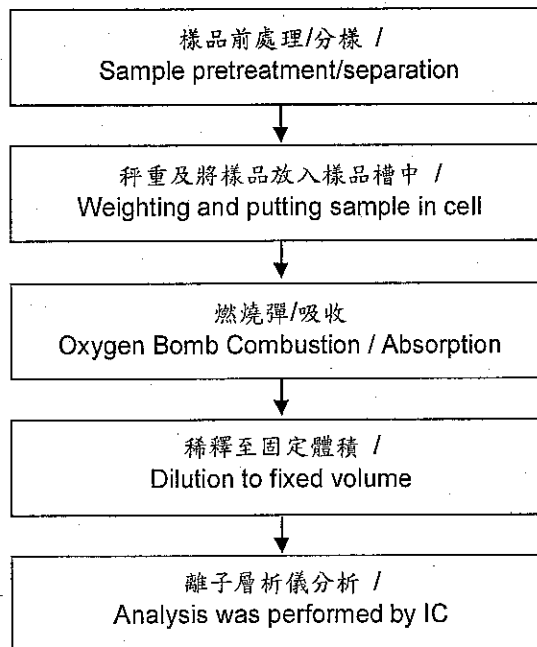
## 測試報告 Test Report

號碼(No.) : CE/2016/A0549      日期(Date) : 2016/10/13      頁數(Page): 11 of 12

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### 鹵素分析流程圖 / Analytical flow chart - Halogen


- 測試人員：陳恩臻 / Technician: Rita Chen
- 測試負責人：張啟興 / Supervisor: Troy Chang



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\* 照片中如有箭頭標示，則表示為實際檢測之樣品/部位。 \*  
(The tested sample / part is marked by an arrow if it's shown on the photo.)

### CE/2016/A0549



### CE/2016/A0549



\*\* 報告結尾 (End of Report) \*\*

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